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MAY 21 2004
PATENT & TRADEMARK OFFICE

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: §
Shang, et al. §
§
Serial No.: 10/024,985 §
§
Filed: December 18, 2001 §
§
Confirmation No.: 4811 §
§
For: FULL GLASS SUBSTRATE DEPOSITION IN PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION §

Group Art Unit: 1763

Examiner: Anna M. Crowell

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING
37 C.F.R. § 1.8
I hereby certify that this correspondence is being deposited on May 19, 2004 with the United States Postal Service as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

5/19/04 Keith M. Tackett
Date Signature: Keith M. Tackett

Dear Sir:

RESPONSE TO OFFICE ACTION DATED FEBRUARY 19, 2004

In response to the Office Action dated February 19, 2004, having a shortened statutory period for response set to expire on May 19, 2004, please enter this response and reconsider the claims pending in the application for reasons discussed below. Applicants confirm election of the species of Group I, claims 1-21. Although Applicants believe that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/5162/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

Amendments to the Specification begin on page 2 of this paper. **Amendments to the Claims** are reflected in the listing of claims which begins on page 4 of this paper. **Remarks** begin on page 8 of this paper.